DEFENSE LOGISTICS AGENCY
DEFENSE SUPPLY CENTER, COLUMBUS
POST OFFICE BOX 3990
COLUMBUS, OH 43216-5000

IN REPLY
REFER TO

DSCC-VQ (VQC-06-011643/Mr. Grammens/614-692-0604/mjg)

SUBJECT: Laboratory Suitability for MIL-STD-883, FSC 5962, MIL-PRF-38535, FSC 5962

Mr. Robert C. Corrao
President
Corwil Technology Corporation
1635 McCarthy Blvd.
Milpitas, CA 95035

Dear Mr. Corrao:

Corwil has demonstrated to the Defense Supply Center, Columbus (DSCC) compliance with MIL-STD-883, the test standard for integrated circuits. Corwil is granted laboratory suitability, effective August 30, 2006, for the facilities, test methods and conditions shown on the enclosure. All testing must be performed in accordance with MIL-PRF-38535 and MIL-STD-883 test methods.

This laboratory suitability is subject to the conditions in DoD 4120.24-M, Defense Standardization Program.

QPL/QML test labs shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products utilizing test methods listed on the enclosure. Failure to provide prior notification may be grounds for removal from QML-38535.

This laboratory suitability is valid until terminated by written notice from DSCC. If warranted, it may be withdrawn by DSCC at any time. Each of these facilities is subject to an audit by DSCC with a minimum notice.

Sincerely,

ROBERT P. EVANS
Chief
Sourcing and Qualification Unit

Enclosure

cc:
Corwil (Dick Nelson)
VQC (Scott Thomas)
VQC (Mike Grammens)

TEST	METHOD/CONDITION	Corwil	Wyle Labs Santa Clara	Other Labs used
Moisture Resistance	1004		X	
Steady State Life Test	1005 A-E		X	
Stabilization Bake	1008 A-D	X		
Salt Atmosphere	1009 A-D		X	
Temperature Cycling	1010 A-C	X	Backup	
Thermal Shock	1011 A-C		X	
Seal	1014 A_1,A_2,C_1	X	Backup	
Burn-in	1015 A-E		X	
Internal Water Vapor Content	1018			Pernicka
Constant Acceleration	2001 A-E	X	Backup	
Mechanical Shock	2002 A-G		X	
Vibration, Variable Frequency	2007 A-G		X	
Solderability	2003		X	
Lead Integrity	2004 B_1,B_2,D		X	
External Visual	2009	X		
Internal Visual	2010 B	X		
Bond Strength	2011/D	X		
Resistance to Solvents	2015		X	
Physical Dimensions	2016	X		
Die Shear Strength	2019	X		
PIND	2020 A-B	X	Backup	
Nondestructive Bond Pull	2023	X		
Lid Torque	2024	X		
Adhesion of Lead Finish	2025	X		
Substrate Attach Strength	2027	X		